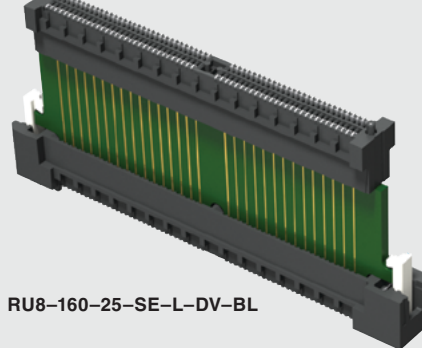
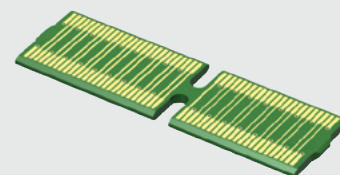




RU8-160-25-SE-L-DV-BL



HSC8-050-02-19-DP

(0.80 mm) .0315"

RU8, HSC8 SERIES

HIGH-SPEED RISER CARD KIT

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?RU8

CONNECTOR

Insulator Material:

Black LCP

Contact:

BeCu

Plating:

Au or Sn over 50 μm (1.27 μm) Ni

Current Rating:

3.1 A per pin (6 adjacent pins powered)

Operating Temp:

-55 °C to +125 °C

EDGE RATE
CONTACT

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (40-60)

RoHS Compliant:

Yes

RECOGNITIONS

For complete scope of

recognitions see

www.samtec.com/quality



Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

RU8 - **1** POSITIONS PER ROW - **STACK HEIGHT** - **SIGNAL ROUTING** - **PLATING OPTION** - **DV** - **BL** - **OTHER OPTION**

40, 50, 60

Kit contains two connectors and one card. Assembly required.

-19
= (19 mm) .748"

-25
= (25 mm) .984"

-30
= (30 mm) 1.180"

-SE
= Single-Ended

-DP
= Differential Pair

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail (Plating for connectors) Plating for Card is Hard Gold

-BL
= Board Locks (Bottom Socket only) (Not available on -19 stack height)

-K
= (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel

Note: Other Gold plating options available.

NO. OF POSITIONS PER SIDE	A	B	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
40	(39.80) 1.567	(51.05) 2.010	40	26
50	(47.80) 1.882	(59.05) 2.325	50	32
60	(55.80) 2.197	(67.05) 2.640	60	38

Note: Some lengths, styles and options are non-standard, non-returnable.

Mates with:

HSEC8

SPECIFICATIONS

For complete specifications see www.samtec.com?HSC8

Conductor:

1/2 oz Copper

Contact Area:

Hard Gold Plated

Insulator: FR-4

RoHS Compliant:

Yes

NO. OF POSITIONS PER SIDE	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
-40	40	26
-50	50	32
-60	60	38

Note:

Some sizes, styles and options are non-standard, non-returnable.

HSC8 - **NUMBER OF POSITIONS PER SIDE** - **CARD STYLE** - **STACK HEIGHT** - **SIGNAL ROUTING**

-040, -050, -060

-02
= (1.60 mm) .062" thick card

-19
= (19 mm) .748"

-25
= (25 mm) .984"

-30
= (30 mm) 1.180"

-SE
= Single-Ended

-DP
= Differential Pair

STACK HEIGHT	A
-19	(14.84) .584
-25	(20.84) .820
-30	(25.84) 1.017

Diagram showing signal routing and dimensions:

No. of Positions per Side x (0.80) .0315 + (4.45) .175

Signal (1.60) .062

Ground

Signal

Ground

-SE -DP

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.